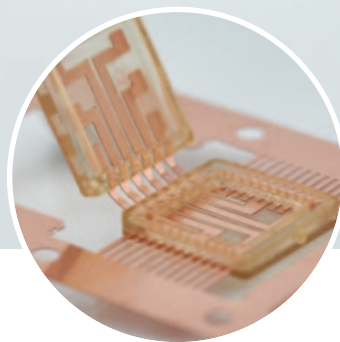
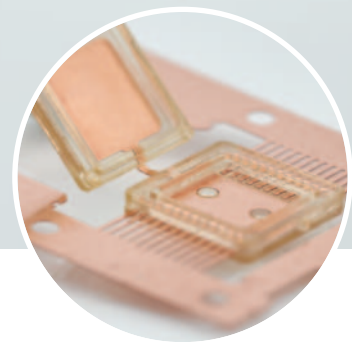


Antenna on package  
without additional  
process steps



I/O-pads for 3D-stack  
without additional  
process steps



Shielding on package  
without additional  
process steps

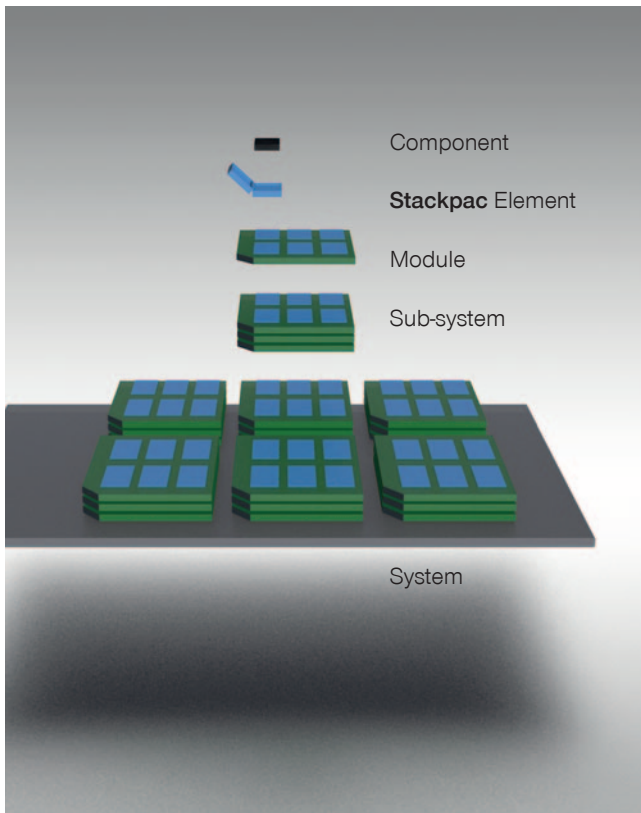
## Possehl Smart Chip Package concept – Stackpac

A new way to design your electronics more modulare! The patented<sup>1)</sup> **Stackpac** concept uses state of the art standard production technologies, which allow a fast and reliable realization in mass production at optimized costs. **Possehl Electronics** is ready to cooperate with you on suitable intelligent housing designs.

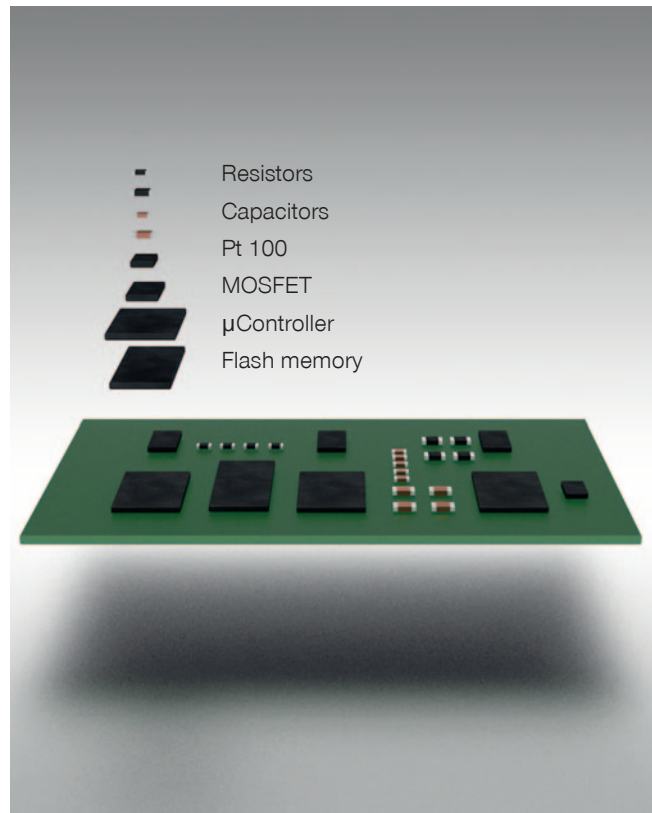
Patented **Stackpac** concept saves  
50 % or more of chip packaging costs<sup>2)</sup>

# Possehl Electronics the Precision the People!

## Modular system with stacked modules



## Traditional electronics systems with components on a PCB



## Advantages of Stackpac at a glance

- **Save 50 % or even more of chip packaging costs**, comparison base is a premolded package with separate functionalized lid.
- **No more complex processes** for structuring and metallization of surface structures.
- **Integrate additional functions** in the housing by adding e.g. heat sinks, antennas or EMC protection.
- Have the chip packages stacked on top of each others **saving space on your PCB by implementing a reliable serial bus connection.**

Detailed technical specifications about **Possehl Smart Chip Package** concept are available on request.

Please contact us:  
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